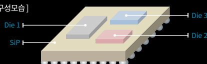
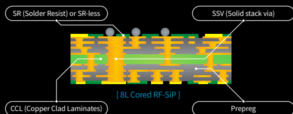
BGA (SiP Module)

개요 OVERVIEW

다수 IC 및 수동소자를 실장하는 Module용 기판

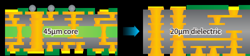
- Radio Frequency 성능 향상 및 패키지 소형화 가능
- 응용 분야 : 5G 모듈, PA (Power Amplifier), SAW Filter, FEM 등



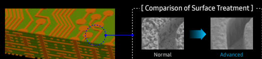


차별화 DIFFERENTIATION

Coreless RF-SiP Substrate : Thin Substrate 구현



성능 향상을 위한 회로 편차 개선 : Low Cu Roughness



주요 사양 KEY SPECIFICATIONS

Layer Structure	Cored	4L~14L
	Coreless	~9L
회로 (Line/Space)		25/25㎛
Surface Finish		Direct Au, Thin ENEPIG Selective ENEPIG